# 3-Channel Ultra High Efficiency LED Driver

# Description

The CAT3643 is a high efficiency fractional charge pump that can drive up to three LEDs programmable by a one wire digital interface. The inclusion of a 1.33x fractional charge pump mode increases device efficiency by up to 10% over traditional 1.5x charge pumps with no added external capacitors.

Low noise input ripple is achieved by operating at a constant switching frequency which allows the use of small external ceramic capacitors. The multi–fractional charge pump supports a wide range of input voltages from 2.4 V to 5.5 V.

The EN/DIM logic input functions as a chip enable and a digital dimming interface for current setting of all LEDs. Six different current ratios are available via the interface.

The device is available in the 16-pad TQFN or 12-pad TDFN 3 mm x 3 mm package with a max height of 0.8 mm.

ON Semiconductor's 1.33x charge pump switching architecture is patented.

#### **Features**

- High Efficiency 1.33x Charge Pump
- Charge Pump: 1x, 1.33x, 1.5x, 2x
- Drives up to 3 LEDs at 32 mA Each
- 1-wire EZDim LED Current Programming
- Power Efficiency up to 92%
- Low Noise Input Ripple in All Modes
- "Zero" Current Shutdown Mode
- Soft Start and Current Limiting
- Short Circuit Protection
- Thermal Shutdown Protection
- 12-pad TDFN and 16-pad TQFN Packages
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

#### **Applications**

- LCD Display Backlight
- Cellular Phones
- Digital Still Cameras
- Handheld Devices



# ON Semiconductor®

http://onsemi.com



TDFN-12 HV2 SUFFIX CASE 511AN



TQFN-16 HV3 SUFFIX CASE 510AD

#### **MARKING DIAGRAMS**

HABF HABG

CAT3643HV2-T2 CAT3643HV2-GT2

JAAF

# **ORDERING INFORMATION**

CAT3643HV3-GT2

CAT3643HV3-T2

Device	Package	Shipping†
CAT3643HV2-T2	TDFN-12	2000 /
(Note 1)	(Pb-Free)	Tape & Reel
CAT3643HV2-GT2	TDFN-12	2000 /
(Note 2)	(Pb-Free)	Tape & Reel
CAT3643HV3-T2	TQFN-16	2000 /
(Note 1)	(Pb-Free)	Tape & Reel
CAT3643HV3-GT2	TQFN-16	2000 /
(Note 2)	(Pb-Free)	Tape & Reel

- †For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.
- 1. Matte-Tin Plated Finish (RoHS-compliant).
- 2. NiPdAu Plated Finish (RoHS-compliant).

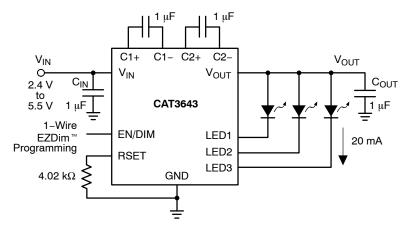


Figure 1. Typical Application Circuit

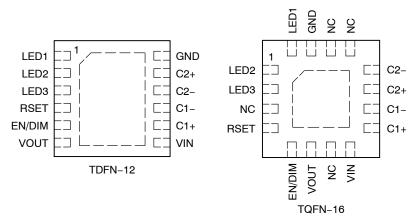


Figure 2. Pin Configurations (Top Views)

The CAT3643 is offered in three different packages. The 12-pad TDFN 3 mm x 3 mm with a max height of 0.8 mm is pin-compatible to the ON Semiconductor CAT3603 LED driver. The 16-pad TQFN 3 mm x 3 mm with max height of 0.8 mm is also offered.

**Table 1. ABSOLUTE MAXIMUM RATINGS** 

Parameter	Rating	Unit
V <sub>IN</sub> , LEDx, C1±, C2±, EN/DIM, RSET voltage	6	V
V <sub>OUT</sub> voltage	7	V
Storage Temperature Range	-65 to +160	°C
Junction Temperature Range	-40 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

**Table 2. RECOMMENDED OPERATING CONDITIONS** 

Parameter	Rating	Unit
V <sub>IN</sub>	2.5 to 5.5	V
Ambient Temperature Range	-40 to +85	°C
I <sub>LED</sub> per LED pin	up to 30	mA
LED Forward Voltage Range	1.3 to 4.3	V

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

NOTE: Typical application circuit with external components is shown above.

# Table 3. ELECTRICAL OPERATING CHARACTERISTICS

(over recommended operating conditions unless specified otherwise)  $V_{IN}$  = 3.6 V, EN = High,  $T_{AMB}$  = 25°C.

Symbol	Name	Conditions	Min	Тур	Max	Units
lα	Quiescent Current	1x mode, no load 1.33x mode, no load 1.5x mode, no load 2x mode, no load		1.0 1.7 2.2 2.4		mA
I <sub>QSHDN</sub>	Shutdown Current	V <sub>EN</sub> = 0 V			1	μΑ
I <sub>LED-ACC</sub>	LED Current Accuracy	( $I_{LEDAVG} - I_{NOMINAL}$ ) / $I_{NOMINAL}$ RSET = 5 kΩ		±2		%
I <sub>LED-DEV</sub>	LED Channel Matching	(I <sub>LED</sub> – I <sub>LEDAVG</sub> ) / I <sub>LEDAVG</sub>		±1.5		%
V <sub>RSET</sub>	RSET Regulated Voltage		0.58	0.6	0.62	V
R <sub>OUT</sub>	Output Resistance (open loop)	1x mode 1.33x mode, V <sub>IN</sub> = 3 V 1.5x mode, V <sub>IN</sub> = 2.7 V 2x mode, V <sub>IN</sub> = 2.4 V		0.8 5 5 10		Ω
Fosc	Charge Pump Frequency	1.33x and 2x mode 1.5x mode	0.8 1	1 1.3	1.3 1.6	MHz
I <sub>SC_MAX</sub>	Output short circuit Current Limit	V <sub>OUT</sub> < 0.5 V		50		mA
I <sub>IN_MAX</sub>	Input Current Limit	V <sub>OUT</sub> > 1 V		250		mA
LED <sub>TH</sub>	1x to 1.33x or 1.33x to 1.5x or 1.5x to 2x Transition Thresholds at any LED pin			130		mV
V <sub>HYS</sub>	1x Mode Transition Hysteresis			400		mV
T <sub>DF</sub>	Transition Filter Delay			500		μs
R <sub>EN/DIM</sub> V <sub>HI</sub> V <sub>LO</sub>	EN/DIM Pin  - Internal Pull-down Resistor  - Logic High Level  - Logic Low Level		1.3	100	0.4	kΩ V V
T <sub>SD</sub>	Thermal Shutdown			150		°C
T <sub>HYS</sub>	Thermal Hysteresis			20		°C
V <sub>UVLO</sub>	Undervoltage lockout (UVLO) threshold		1.6	1.8	2.0	V

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

# Table 4. RECOMMENDED EN/DIM TIMING

(For 2.4 V  $\leq$  V<sub>IN</sub>  $\leq$  5.5 V, over full ambient temperature range  $-40^{\circ}C$  to  $+85^{\circ}C$ .)

Symbol	Name	Conditions	Min	Тур	Max	Units
T <sub>SETUP</sub>	EN/DIM setup from shutdown		10			μs
T <sub>LO</sub>	EN/DIM program low time		0.2		100	μs
T <sub>HI</sub>	EN/DIM program high time		0.2			μs
T <sub>PWRDWN</sub>	EN/DIM low time to shutdown		1.5			ms
T <sub>LED</sub>	LED current settling time			40		μs

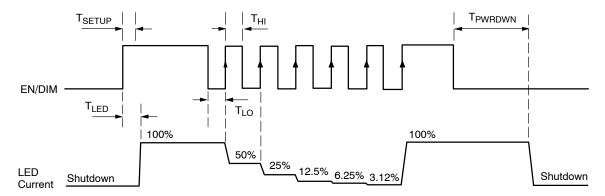


Figure 3. EN/DIM Digital Dimming Timing Diagram

# **LED Current Setting**

The nominal LED current is set by the external resistor connected between the RSET pin and ground. Table 5 lists standard resistor values for several LED current settings.

**Table 5. RESISTOR RSET AND LED CURRENT** 

LED Current (mA)	RSET (kΩ)
2	40.0
5	15.8
10	7.87
15	5.23
20	4.02
25	3.16
30	2.67

# TYPICAL PERFORMANCE CHARACTERISTICS

 $(V_{IN}=3.6~V,~I_{OUT}=60~mA~(3~LEDs~at~20~mA),~C_{IN}=C_{OUT}=C_1=C_2=1~\mu\text{F},~T_{AMB}=25^{\circ}\text{C}~unless~otherwise~specified.)$ 

QUIESCENT CURRENT (mA)

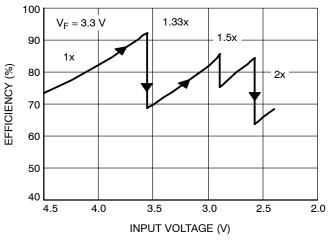


Figure 4. Efficiency vs. Input Voltage

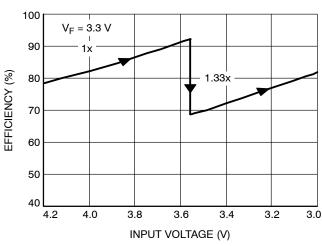


Figure 5. Efficiency vs. Li-Ion Voltage

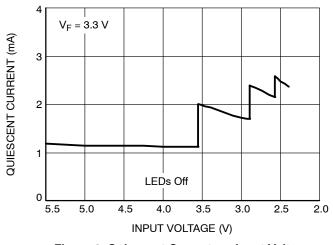


Figure 6. Quiescent Current vs. Input Voltage

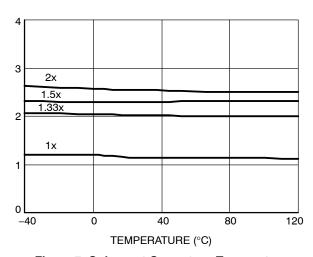


Figure 7. Quiescent Current vs. Temperature

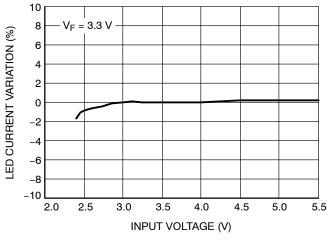


Figure 8. LED Current Change vs. Input Voltage

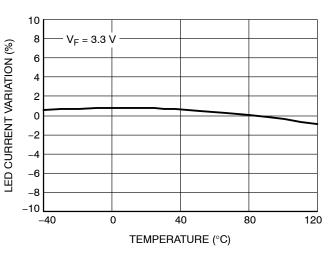
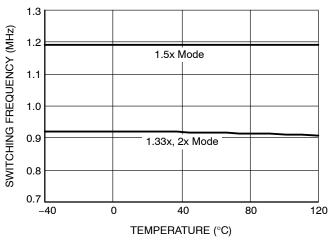


Figure 9. LED Current Change vs. Temperature

# TYPICAL PERFORMANCE CHARACTERISTICS

 $(V_{IN}=3.6~V,~I_{OUT}=60~mA~(3~LEDs~at~20~mA),~C_{IN}=C_{OUT}=C_1=C_2=1~\mu\text{F},~T_{AMB}=25^{\circ}C~unless~otherwise~specified.)$ 



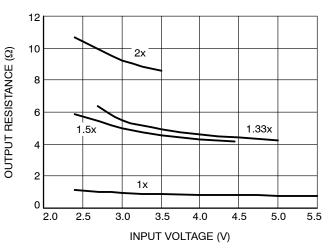
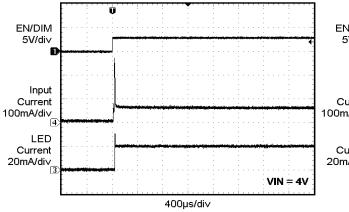


Figure 10. Switching Frequency vs. Temperature

Figure 11. Output Resistance vs. Input Voltage



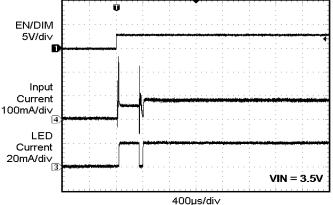
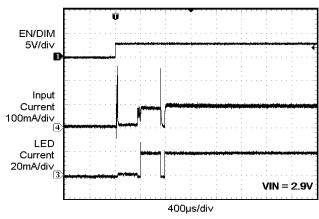


Figure 12. Power Up in 1x Mode

Figure 13. Power Up in 1.33x Mode





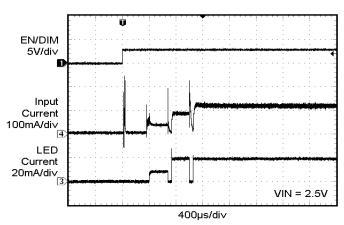


Figure 15. Power Up in 2x Mode

### TYPICAL PERFORMANCE CHARACTERISTICS

 $(V_{IN}=3.6~V,~I_{OUT}=60~mA~(3~LEDs~at~20~mA),~C_{IN}=C_{OUT}=C_1=C_2=1~\mu\text{F},~T_{AMB}=25^{\circ}C~unless~otherwise~specified.)$ 

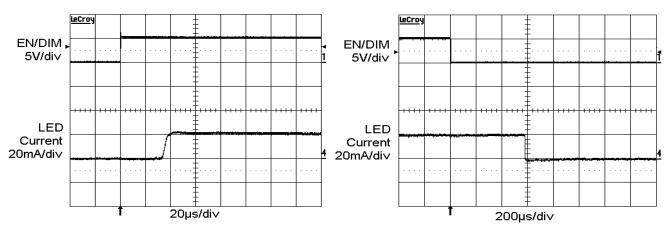


Figure 16. Power Up Delay (1x Mode)

Figure 17. Power Down Delay (1x Mode)

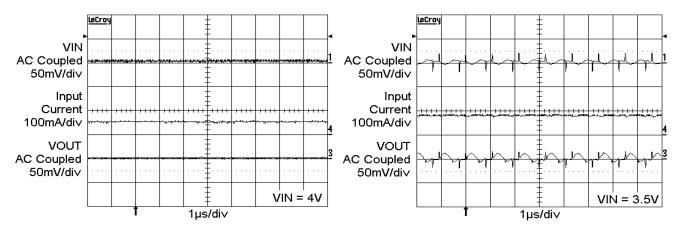


Figure 18. Operating Waveforms in 1x Mode

Figure 19. Switching Waveforms in 1.33x Mode

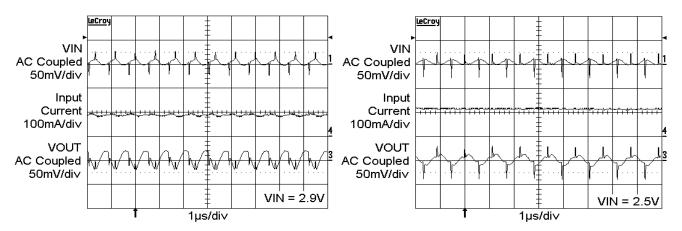
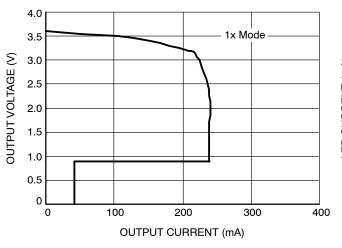


Figure 20. Switching Waveforms in 1.5x Mode

Figure 21. Switching Waveforms in 2x Mode

# TYPICAL PERFORMANCE CHARACTERISTICS

 $(V_{IN}=3.6~V,~I_{OUT}=60~mA~(3~LEDs~at~20~mA),~C_{IN}=C_{OUT}=C_1=C_2=1~\mu\text{F},~T_{AMB}=25^{\circ}C~unless~otherwise~specified.)$ 



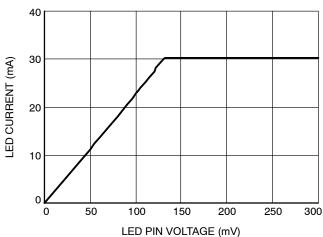
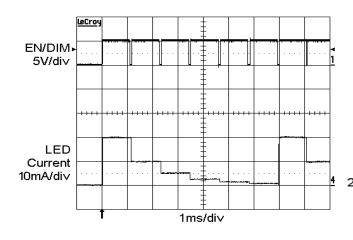


Figure 22. Foldback Current Limit

Figure 23. LED Current vs. LED Pin Voltage



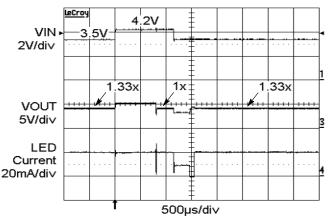
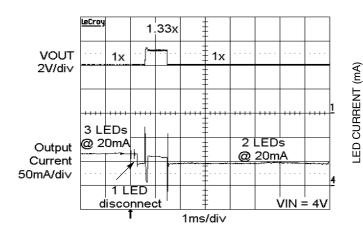


Figure 24. Dimming Waveform

Figure 25. Line Transient Response



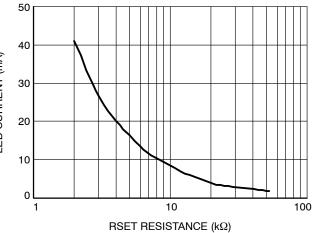


Figure 26. Disconnecting a Single LED

Figure 27. LED Current vs. RSET

**Table 6. PIN DESCRIPTION** 

Name	Function
LED1	LED1 cathode terminal.
LED2	LED2 cathode terminal.
LED3	LED3 cathode terminal.
RSET	Connect resistor RSET to set the LED current.
EN/DIM	Device enable (active high) and Dimming Control.
VOUT	Charge pump output connected to the LED anodes.
VIN	Charge pump input, connect to battery or supply.
C1+	Bucket capacitor 1 Positive terminal
C1-	Bucket capacitor 1 Negative terminal
C2+	Bucket capacitor 2 Positive terminal
C2-	Bucket capacitor 2 Negative terminal
GND	Ground Reference
NC	Not connected inside package.
GND	Connect to GND on the PCB.

#### **Pin Function**

VIN is the supply pin for the charge pump. A small 1  $\mu$ F ceramic bypass capacitor is required between the VIN pin and ground near the device. The operating input voltage range is from 2.5 V to 5.5 V. Whenever the input supply falls below the under-voltage threshold (1.8 V), all the LED channels are disabled and the device enters shutdown mode.

**EN/DIM** is the enable and one wire dimming input for all LED channels. Levels of logic high and logic low are set at 1.3 V and 0.4 V respectively. When EN/DIM is initially taken high, the device becomes enabled and all LED currents are set to the full scale according to the resistor  $R_{SET}$ . To place the device into "zero current" shutdown mode, the EN/DIM pin must be held low for at least 1.5 ms.

**VOUT** is the charge pump output that is connected to the LED anodes. A small 1  $\mu$ F ceramic bypass capacitor is required between the VOUT pin and ground near the device.

**GND** is the ground reference for the charge pump. The pin must be connected to the ground plane on the PCB.

C1+, C1- are connected to each side of the ceramic bucket capacitor  $C_1$ .

C2+, C2- are connected to each side of the ceramic bucket capacitor  $C_2$ .

**LED1, LED2, LED3** provide the internal regulated current sources for each of the LED cathodes. These pins enter high-impedance zero current state whenever the device is placed in shutdown mode.

**TAB** is the exposed pad underneath the package. For best thermal performance, the tab should be soldered to the PCB and connected to the ground plane.

**RSET** is connected to the resistor (R<sub>SET</sub>) to set the full scale current for the LEDs. The voltage at this pin regulated to 0.6 V. The ground side of the external resistor should be star connected back to the GND of the PCB. In shutdown mode, RSET becomes high impedance.

### **Block Diagram**

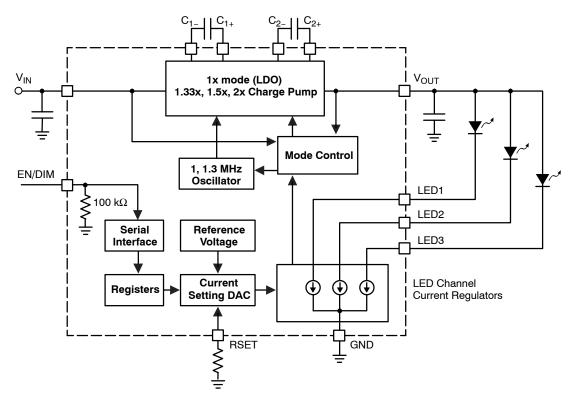


Figure 28. CAT3643 Functional Block Diagram

### **Basic Operation**

At power-up, the CAT3643 starts operating in 1x mode where the output will be approximately equal to the input supply voltage (less any internal voltage losses). If the output voltage is sufficient to regulate all LED currents, the device remains in 1x operating mode.

If the input voltage is insufficient or falls to a level where the regulated currents cannot be maintained, the device automatically switches into 1.33x mode (after a fixed delay time of about  $400~\mu s$ ). In 1.33x mode, the output voltage is approximately equal to 1.33 times the input supply voltage (less any internal voltage losses).

The above sequence repeats in the 1.33x and 1.5x mode until the driver enters the 2x mode. In 1.5x mode, the output voltage is approximately equal to 1.5 times the input supply voltage. While in 2x mode, the output is approximately equal to 2 times the input supply voltage.

If the device detects a sufficient input voltage is present to drive all LED currents in 1x mode, it will change automatically back to 1x mode. This only applies for changing back to the 1x mode. The difference between the input voltage when exiting 1x mode and returning to 1x mode is called the 1x mode transition hysteresis ( $V_{HYS}$ ) and is about 500 mV.

#### **LED Current Selection**

At power-up, the initial LED current is set to full scale (100% brightness) by the external resistor R<sub>SET</sub> as follows:

$$LED \ current = \ 132 \times \frac{0.6 \ V}{R_{SET}}$$

The EN/DIM pin has two primary functions. One function enables and disables the device. The other function is LED current dimming with six different levels by pulsing the input signal, as shown on Figure 29. On each consecutive pulse rising edge, the LED current is divided by half to 50%, then 25%, 12.5%, 6.25% and 3.125% dimming levels.

Pulses faster than the minimum  $T_{LO}$  may be ignored and filtered by the device. Pulses longer than the maximum  $T_{LO}$  may shutdown the device.

The LED driver enters a "zero current" shutdown mode if EN/DIM is held low for 1.5 ms or more.

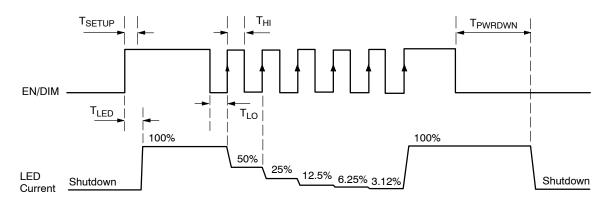


Figure 29. EN/DIM Digital Dimming Timing Diagram

**Table 7. LED CURRENT DIMMING LEVELS** 

EN/DIM # of Pulses *	R <sub>SET</sub> Gain	LED Current
EN = High	132	132 x 0.6 V / R <sub>SET</sub>
1 <sup>st</sup>	66	66 x 0.6 V / R <sub>SET</sub>
2 <sup>nd</sup>	33	33 x 0.6 V / R <sub>SET</sub>
3rd	16.5	16.5 x 0.6 V / R <sub>SET</sub>
4 <sup>th</sup>	8.25	8.25 x 0.6 V / R <sub>SET</sub>
5 <sup>th</sup>	4.125	4.125 x 0.6 V / R <sub>SET</sub>
6 <sup>th</sup>	132	132 x 0.6 V / R <sub>SET</sub>
x <sup>th</sup>	Device cycling through gain selection	GAIN x 0.6 V / R <sub>SET</sub>

<sup>\*</sup> The gain is changed on the rising edges of the EN/DIM input.

#### **Unused LED Channels**

For applications not requiring all the channels, it is recommended the unused LED pins be tied directly to  $V_{OUT}$  (see Figure 30).

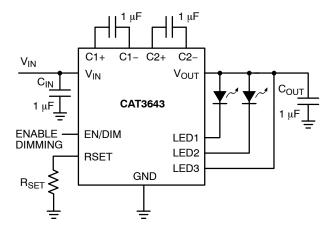


Figure 30. Application with 2 LEDs

#### **Protection Mode**

If an LED is disconnected, the driver senses that and automatically ignores that channel. When all LEDs are disconnected, the driver goes to 1x mode where the output is equal to the input voltage.

As soon as the output exceeds about 6 V, the driver resets itself and reevaluate the mode.

If the die temperature exceeds  $+150^{\circ}$ C, the driver will enter a thermal protection shutdown mode. When the device temperature drops by about 20°C, the device will resume normal operation.

#### **LED Selection**

LEDs with forward voltages ( $V_F$ ) ranging from 1.3 V to 4.3 V may be used. Selecting LEDs with lower  $V_F$  is recommended in order to improve the efficiency by keeping the driver in 1x mode longer as the battery voltage decreases.

For example, if a white LED with a  $V_F$  of 3.3 V is selected over one with  $V_F$  of 3.5 V, the driver will stay in 1x mode for lower supply voltage of 0.2 V. This helps improve the efficiency and extends battery life.

#### **External Components**

The driver requires four external 1  $\mu$ F ceramic capacitors for decoupling input, output, and for the charge pump. Both capacitors type X5R and X7R are recommended for the LED driver application. In all charge pump modes, the input current ripple is kept very low by design and an input bypass capacitor of 1  $\mu$ F is sufficient.

In 1x mode, the device operates in linear mode and does not introduce switching noise back onto the supply.

#### **Recommended Layout**

In charge pump mode, the driver switches internally at a high frequency. It is recommended to minimize trace length to all four capacitors. A ground plane should cover the area under the driver IC as well as the bypass capacitors. Short connection to ground on capacitors  $C_{IN}$  and  $C_{OUT}$  can be implemented with the use of multiple via. A copper area matching the TQFN exposed pad (TAB) must be connected to the ground plane underneath. The use of multiple via improves the package heat dissipation.

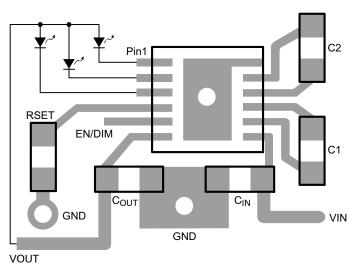
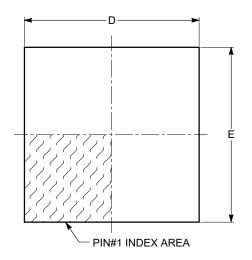
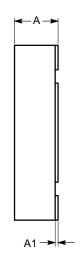


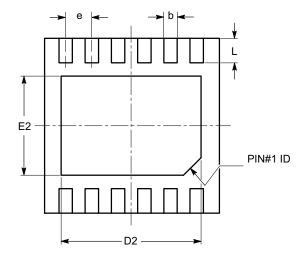
Figure 31. TDFN-12 Recommended Layout

# **PACKAGE DIMENSIONS**

TDFN12, 3x3 CASE 511AN ISSUE A





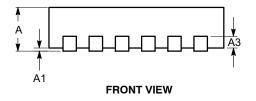


**TOP VIEW** 

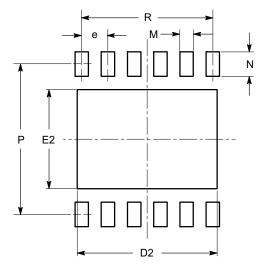
SIDE VIEW	SI	DE	VI	E١	N
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**BOTTOM VIEW** 

SYMBOL	MIN	NOM	MAX
Α	0.70	0.75	0.80
A1	0.00	0.02	0.05
А3	0.178	0.203	0.228
b	0.18	0.23	0.30
D	2.90	3.00	3.10
D2	2.30	2.40	2.50
E	2.90	3.00	3.10
E2	1.55	1.70	1.75
е		0.45 BSC	
L	0.30	0.40	0.50
М	0.25	0.30	0.35
N	0.60	0.70	0.80
Р	2.70	3.00	3.10
R	2.25 TYP		



# RECOMMENDED LAND PATTERN

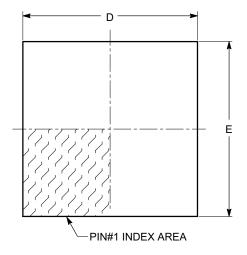


# Notes:

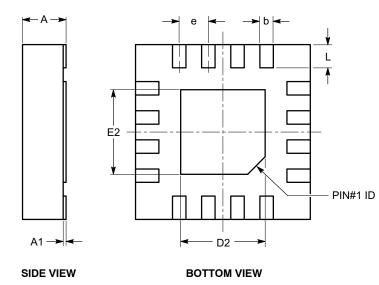
- (1) All dimensions are in millimeters.(2) Complies with JEDEC MO-229.

# **PACKAGE DIMENSIONS**

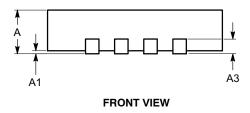
TQFN16, 3x3 CASE 510AD ISSUE A



**TOP VIEW** 



SYMBOL	MIN	NOM	MAX
Α	0.70	0.75	0.80
A1	0.00	0.02	0.05
A3		0.20 REF	
b	0.18	0.25	0.30
D	2.90	3.00	3.10
D2	1.40		1.80
E	2.90	3.00	3.10
E2	1.40		1.80
е	0.50 BSC		
L	0.30	0.40	0.50



#### Notes:

- (1) All dimensions are in millimeters.
- (2) Complies with JEDEC MO-220.
- 3. All packages are RoHS-compliant (Lead-free, Halogen-free).
- 4. The standard lead finish is NiPdAu.
- 5. For additional package and temperature options, please contact your nearest ON Semiconductor Sales office.

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